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FIG. 1

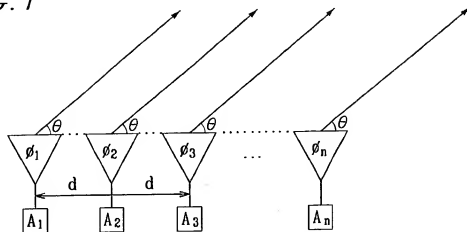


FIG. 2A

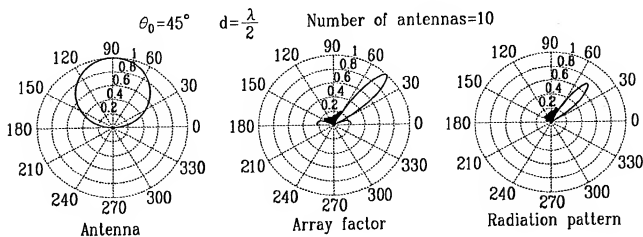
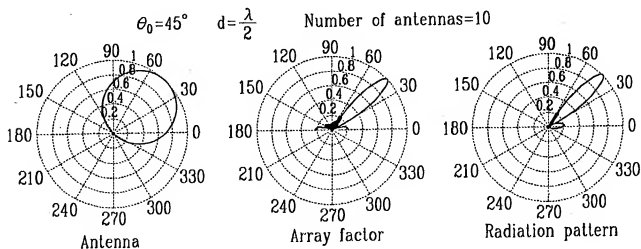


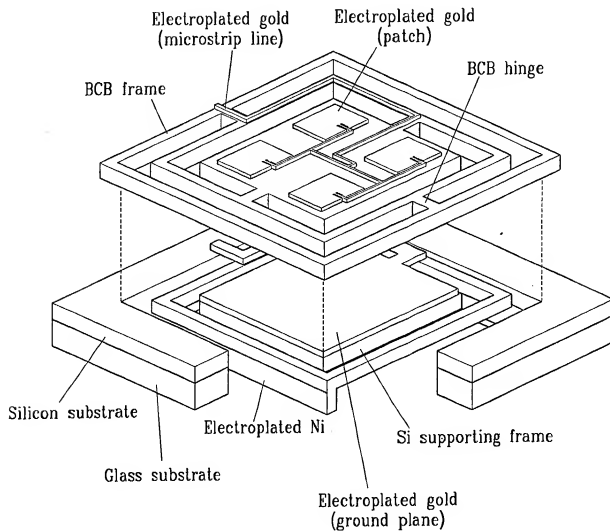
FIG. 2B



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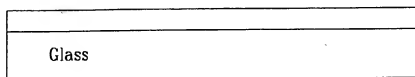
FIG. 3



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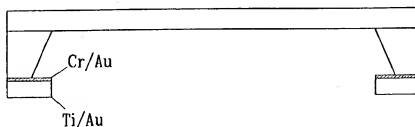
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FIG. 4A



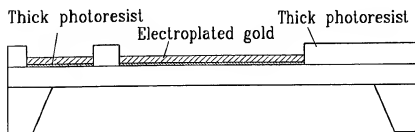
- * Anodic bonding of glass & silicon
- * Thinning of silicon using KOH
- * CMP of silicon

FIG. 4B



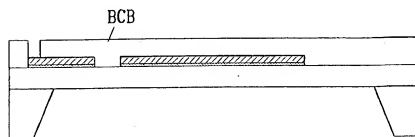
- * Cr/Au deposition
- * Photolithography #1
- * Au/Cr etch
- * Hardbake of photoresist
- * Glass etching

FIG. 4C



- * 1st seed layer deposition
- * Photolithography #2
- * Electroplating

FIG. 4D



- * PR strip
- * Seed layer etching
- * BCB coating & baking
- * BCB patterning

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FIG. 4E

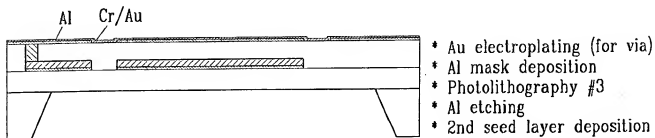


FIG. 4F

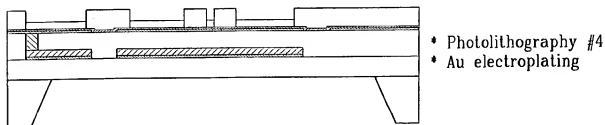


FIG. 4G

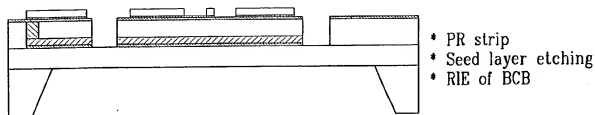
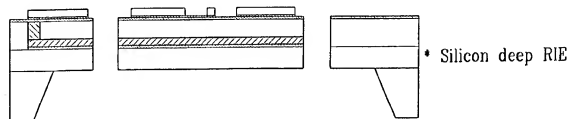


FIG. 4H



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FIG. 5

